# High Reliability NPN Silicon Phototransistor



OP602, OP603, OP604 (TX, TXV) OP604 (S)

#### Features:

- Miniature hermetically sealed package
- Wide range of collector currents
- Ideal for direct mounting to PCBoard
- TX, TXV & S devices are processed to MIL-PRF-19500



#### **Description:**

Each device in the **OP600** high reliability series consists of a high-reliability NPN silicon phototransistor that is mounted in a glass-lensed miniature hermetically sealed "pill" package with an 18° half angle, as measured from the optical axis to the half-power point.

After electrical testing by manufacturing, devices are processed to OPTEK's 100 percent screening program, which is patterned after MIL-PRF-19500. *Components in the high reliability OP600 series are mechanically and spectrally matched to the OP223 and OP224 high reliability series of infrared emitting diodes.* 

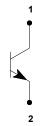
TX, TXV and S devices are processed to OPTEK's military screening program patterned after MIL-PRF-19500.

<u>Please refer to Application Bulletins 208 and 210 for additional design information and reliability (degradation) and to Application Bulletin OP202 for pill-type soldering to PCBoard.</u>

#### **Applications:**

- · Non-contact reflective object sensor
- Assembly line automation
- Machine automation
- Machine safety
- End of travel sensor
- Door sensor

Part Number	Light Current I <sub>C(ON)</sub> (mA) Min / Max	V <sub>CE</sub> Typ / Max	Input Power E <sub>E</sub> (mW/cm <sup>2</sup> )	Viewing Angle
OP602TX	2.00 / 5.00		20.0	35°
OP602TXV	2.00 / 3.00	5 / 50		
OP603TX	4.00 / 8.00			
OP603TXV	4.00 / 8.00			
OP604S				
OP604TX	7.00 / NA			
OP604TXV				



Pin #	Pin # Sensor	
1	Collector/Cathode	
2	Emitter/Anode	

	[2.79] _ .110		Ø.032±.003	APERTURE [0.51±0.10]
[1.65±0.10] .065±.004	-	MEASUREMENT SURFACE		.020±.004
[1.52±0.05] Ø.060±.002				2.24±0.10] .088±.004
1	[2.16±0.10]	0.25 0.13 0.10 .005		-2
	.0651.004		DIMENSIONS ARE IN:	[ MILLIMETERS] INCHES

## High Reliability NPN Silicon Phototransistor



OP602, OP603, OP604 (TX, TXV) OP604 (S)

### Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)

**Electrical Characteristics** (T<sub>A</sub> = 25°C unless otherwise noted)

Emitter-Collector Breakdown Voltage

Collector-Emitter Saturation Voltage

Storage Temperature Range	-65° C to +150° C
Operating Temperature Range	-55° C to +125° C
Collector-Emitter Voltage	50 V
Emitter-Collector Voltage	7.0 V
Soldering Temperature (5 seconds with soldering iron) <sup>(1)</sup>	260° C
Power Dissipation <sup>(2)</sup>	50 mW

Input Diode						
SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS	TEST CONDITIONS
I <sub>C (ON)</sub>	On-State Collector Current OP602TX, OP602TXV OP603TX, OP603TXV OP604TX, OP604TXV, OP604S	2 4 7	-	5 8 -	mA	$V_{CE} = 5.0 \text{ V, } E_E = 20 \text{ mW/cm}^{2(3)(4)}$
I <sub>CEO</sub>	Collector Dark Current	-	-	25	nA	$V_{CE} = 10.0 \text{ V}, E_E = 0$
		-	-	100	μΑ	$V_{CE} = 30.0 \text{ V}, E_E = 0 T_A = 100^{\circ} \text{ C}$
V <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage	50	-	-	V	I <sub>C</sub> = 100 μA, E <sub>E</sub> = 0

7

0.4

20

20

μs

#### Notes:

 $V_{(BR)ECO}$ 

 $V_{\text{CE(SAT)}}$ 

 $t_{\text{r}}$ 

- (1) Refer to Application Bulleting 202, which discusses proper techniques for soldering pill-type devices to PCBoards.
- (2) No clean or low solids. RMA flux is recommended. Duration can be extended to 10 seconds maximum when wave soldering.
- (3) Derate linearly 0.5 mW/° C above 25° C.

Rise Time

Fall Time

- (4) Junction temperature maintained at 25° C.
- (5) Light source is an unfiltered tungsten lamp operating at CT=2870 K or equivalent source.

Issue B 08/2016 Page 2

 $I_C = 100 \mu A, E_E = 0$ 

RL = 100  $\Omega^{(2)(3)(4)}$ 

 $V_{CC} = 30 \text{ V}, I_C = 1.00 \text{ mA},$ 

 $I_C = 0.4 \text{ mA}, E_E = 20 \text{ mW/cm}^{(2)(3)(4)}$